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## ABSTRACT

A semiconductor package structure includes a control unit and a memory unit. The control unit includes a first wafer and a second wafer that are vertically stacked. The memory unit is disposed on the second wafer of the control unit. The memory unit includes multiple third wafers and a fourth wafer that are stacked vertically. The memory unit overlaps the control unit in a normal direction of the semiconductor package structure. In addition, a manufacturing method of the semiconductor package structure is provided.

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